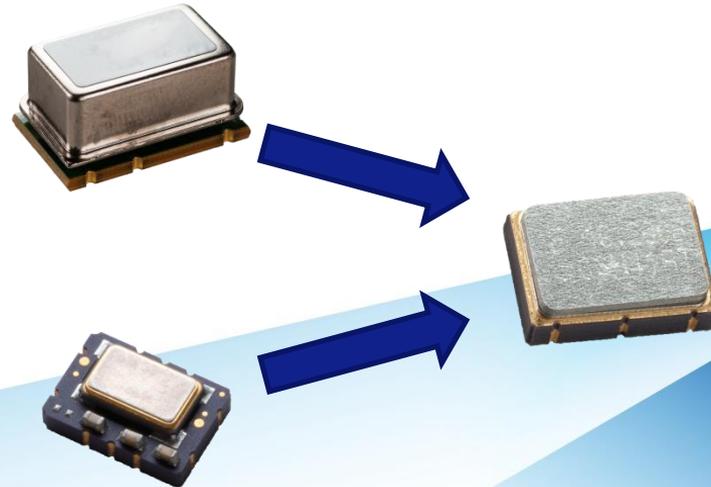
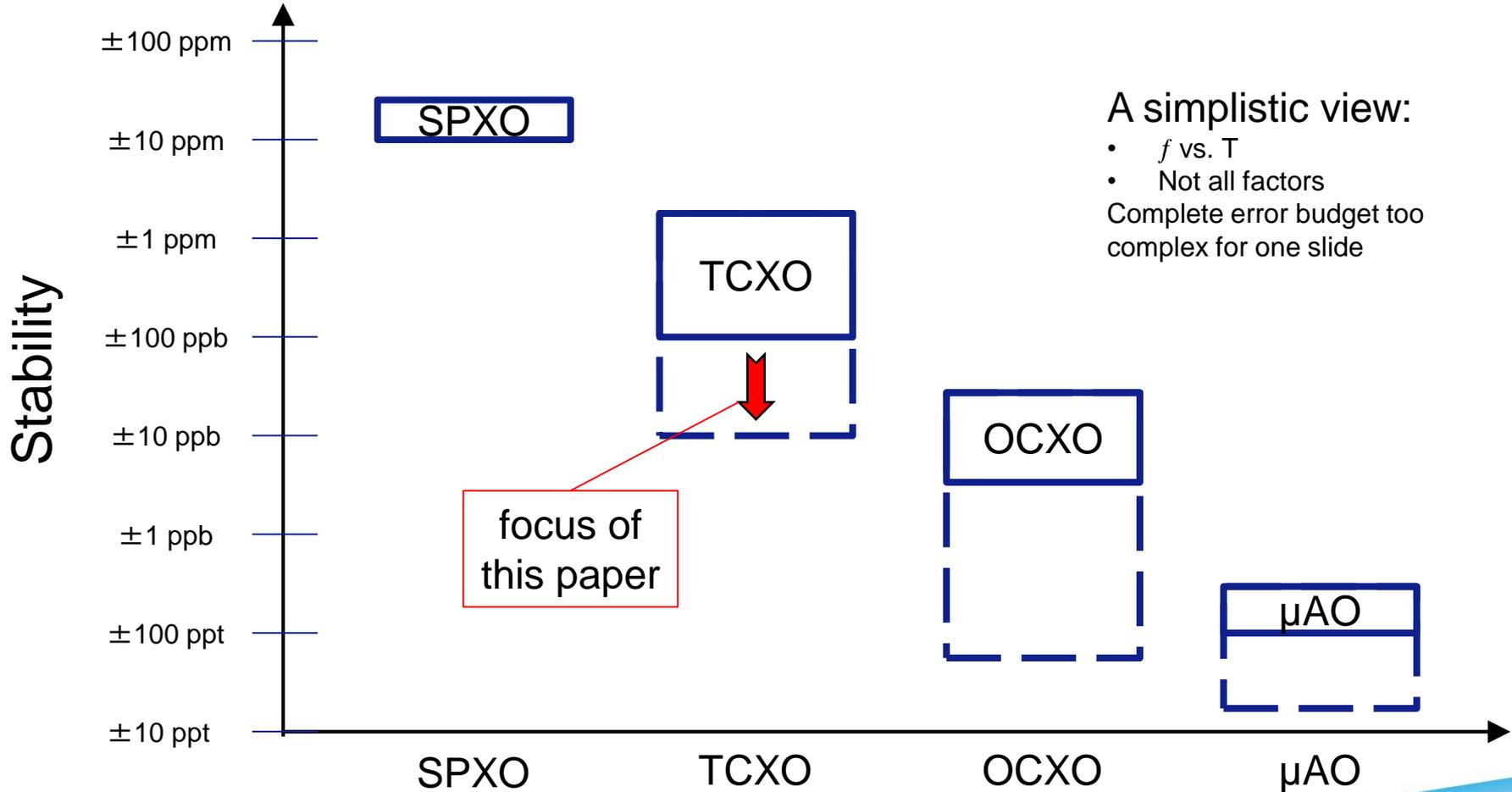


The Next Frontier in TCXO Performance

Chris McCormick
Allan Armstrong
WSTS 2018
June 21, 2018



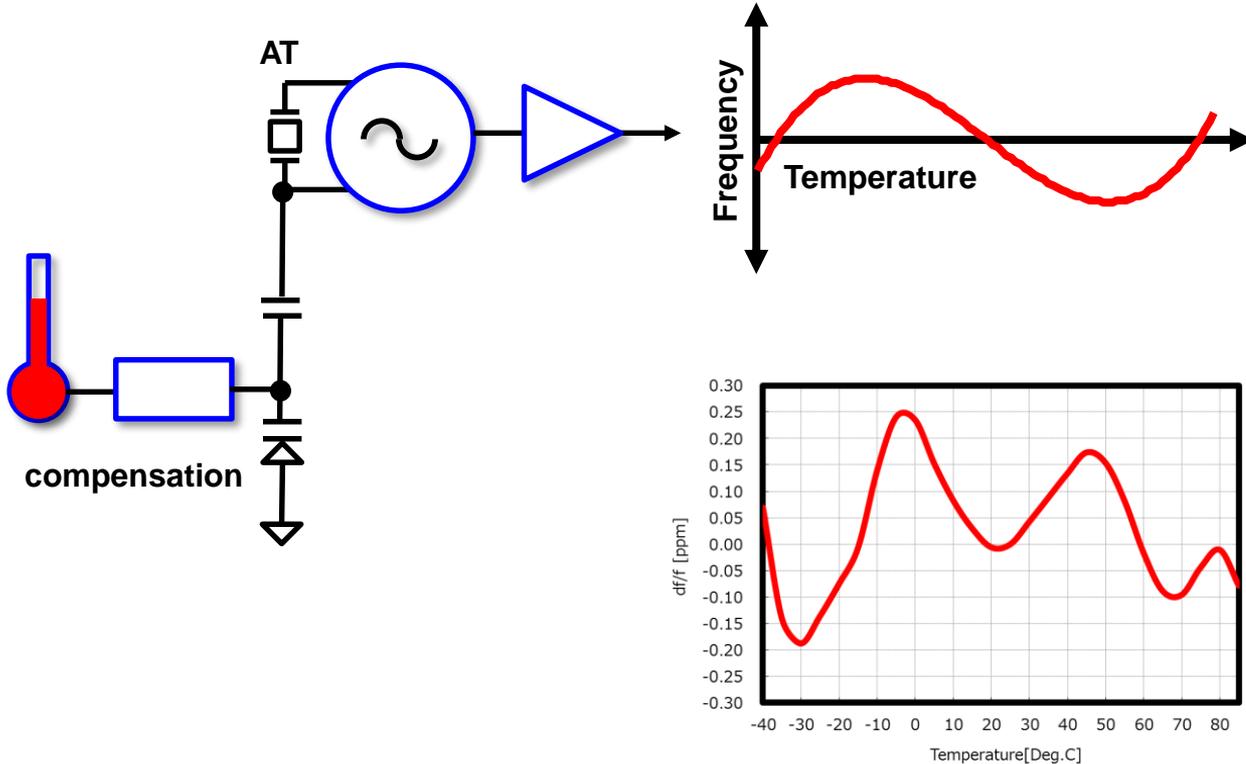
Where are we today?



A simplistic view:

- f vs. T
 - Not all factors
- Complete error budget too complex for one slide

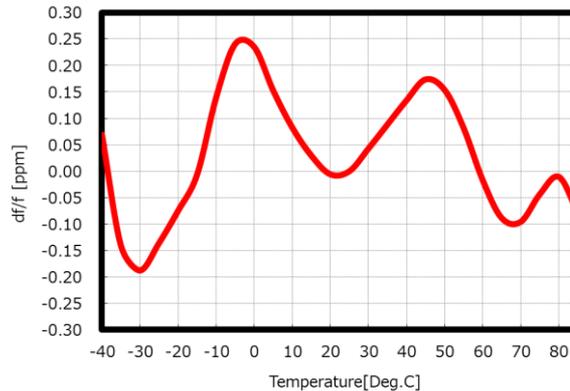
Basics – How a TCXO Works



f vs. $T \approx \pm 10$ ppm
< ± 20 ppm

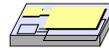
controlled by:

- cut angle
- crystal shape
- crystal dimensions

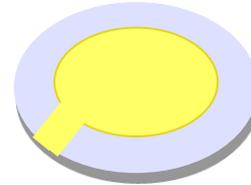


f vs. T	Compensation
± 2 ppm	10x
± 1 ppm	20x
± 0.5 ppm	40x
± 0.28 ppm	70x
± 0.1 ppm	200x
± 0.01 ppm	2000x

Basics – How an OCXO Works

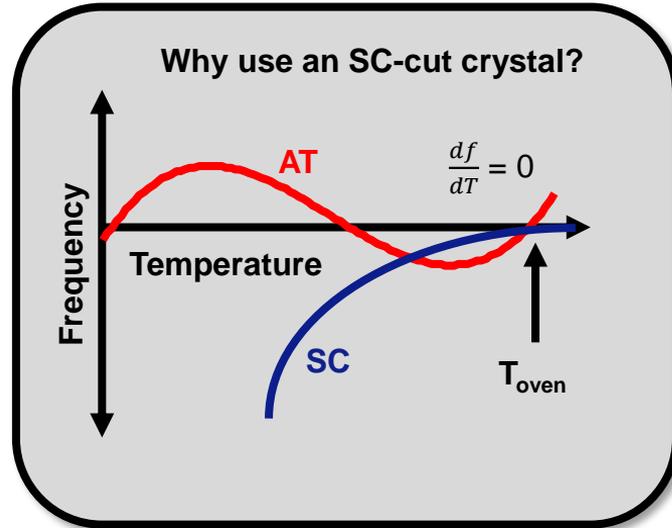
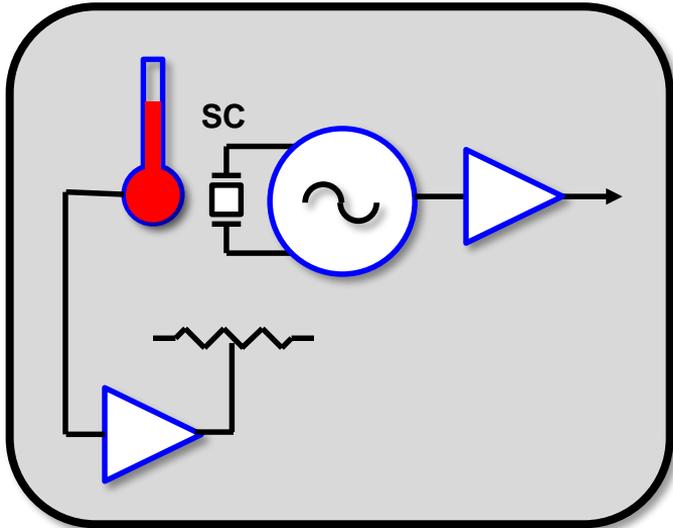


AT



SC

- Size
- Shape
- Cut angle
- Stress



Characteristics of TCXOs vs. OCXOs

What We have Today

Performance

	TCXO	OCXO
f vs. T	$\pm 0.1-0.28$ ppm	$\pm 10-50$ ppb
ADEV @ 1s	1E-9	1E-10
Aging 20-yr	$< \pm 3$ ppm	$< \pm 1$ ppm
Aging 24-hr	$< \pm 40$ ppb	$< \pm 1$ ppb
Airflow	ok	Much better

Practicality

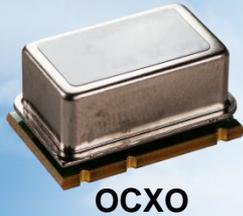
	TCXO	OCXO
Size (WxL)	5x3.2	25x22 21x13 14x9
Size (H)	1.5-2.0	9-12
Cost	\$\$	\$\$\$
Power	$\ll 30$ mW	$< 1-2.5$ W
Reliability	Much better	ok



What Else Needs to be Done?

Performance

- f vs. T
- Wander
- Aging
- Holdover
- Airflow



Practicality

- Size
- Cost
- Power
- Reliability



How do we get there?

- Compensation & Calibration Techniques
- SPC & Manufacturing Discipline
- IC Design
- Mechanical & Thermal Design
- Packaging Technology
- Crystal Design & Fabrication Techniques

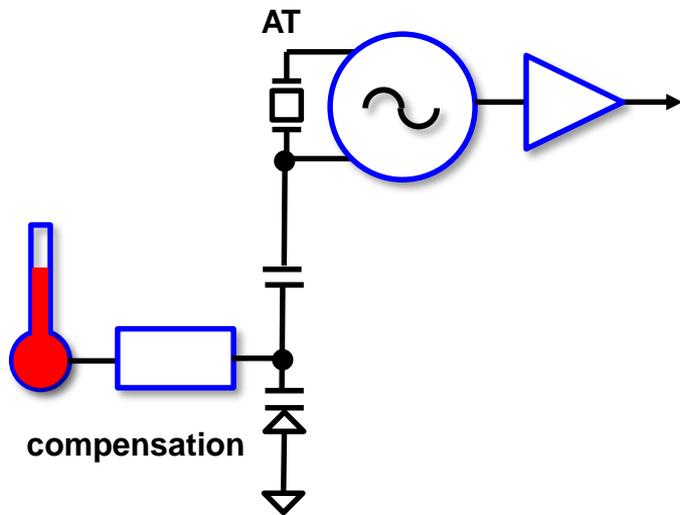
How can we make TCXOs perform like OCXOs?

Existing State of the Art – Recent Innovations

1. **IC design & calibration techniques** – f vs. T
2. **XTAL design** – wander
3. **Package & structure** (thermal design) – airflow & stability for small T variations

What do we need to do next?

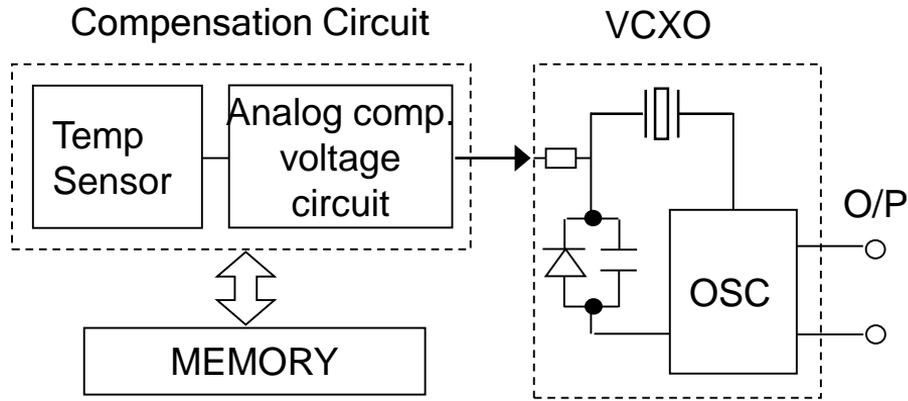
TCXO Concept – Compensation



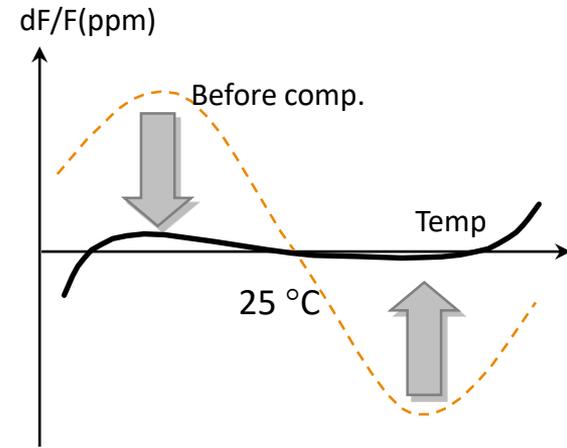
2 Important Choices:

1. Analog vs. Digital
2. How do you compensate?

Analog Compensation



Analog Compensation Method

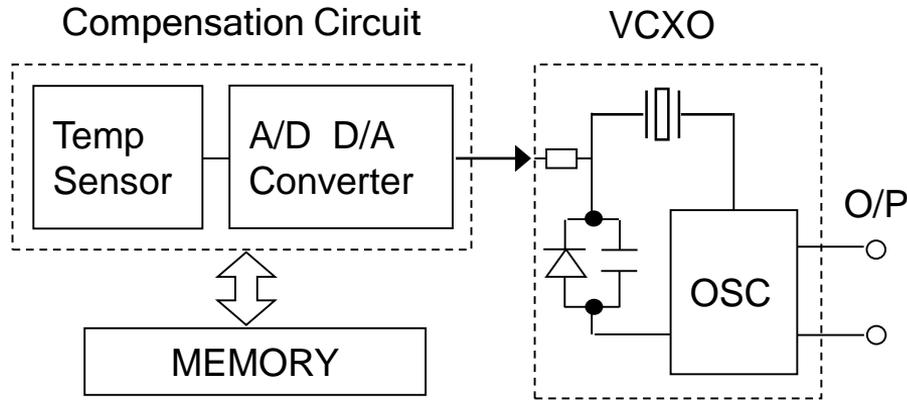


Advantage: No discrete phase jumps

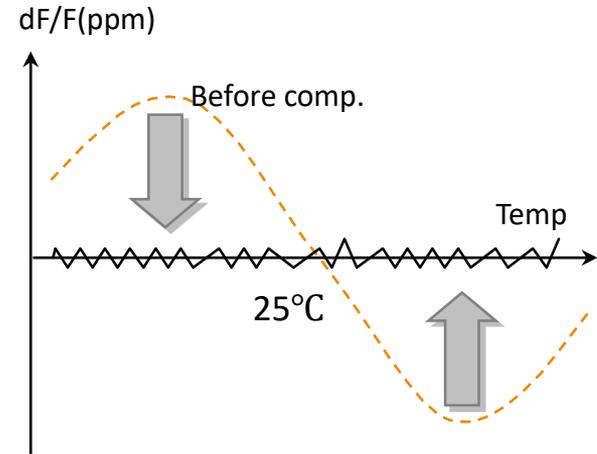
Challenge: fitting error

- Crystal cutting & design optimization
- Calibration techniques – accuracy vs. cost

Digital Compensation



Digital Compensation Method



Advantage: less fitting error (lots of points!)

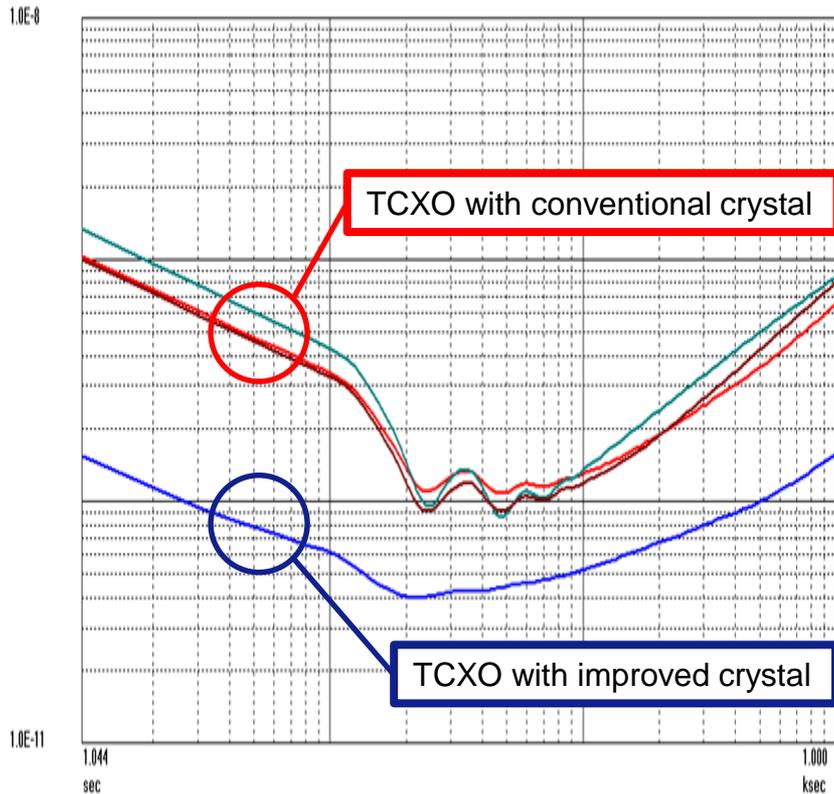
Challenge: discrete phase jumps

- Easy answer: resolution < stability
- How well can you measure temperature? How well do you know your crystal?

Short-Term Stability (Wander)

Microsemi TimeMonitor Analyzer (file=01187.dal)
Root Allan Variance; Overlapping Samples; Fo=20.00 MHz; Fs=957.4 mHz; 2016/05/13; 09:21:25

ADEV

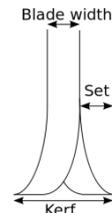


Crystal Design Improvements

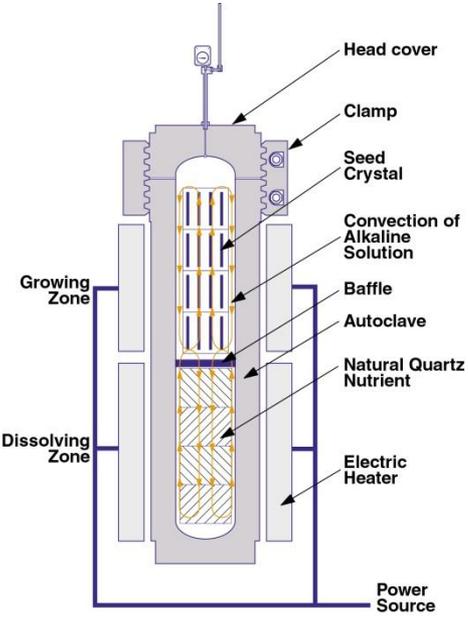
① Material Purity



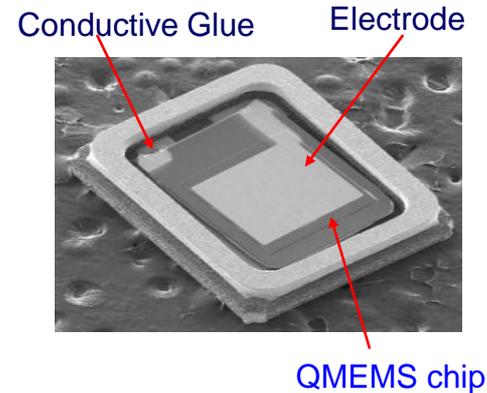
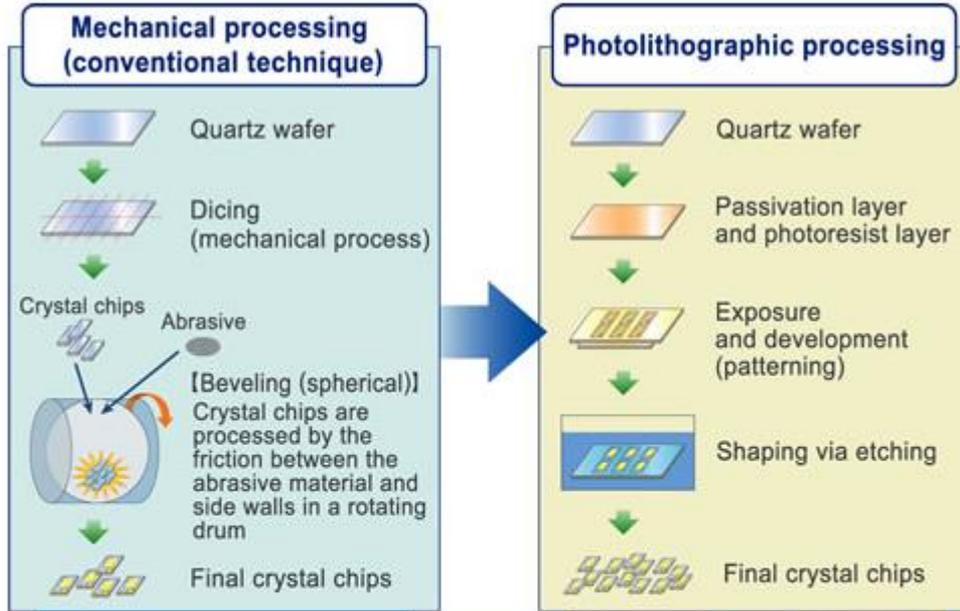
② Crystal Processing



Material Purity (Autoclave)



Crystal Processing



Resulting Shape (cross section)

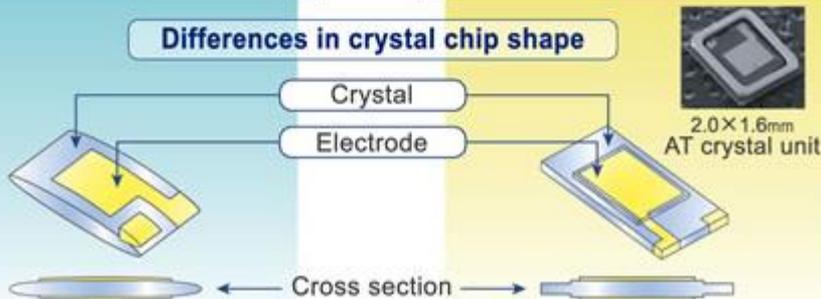


Mechanical (beveled)

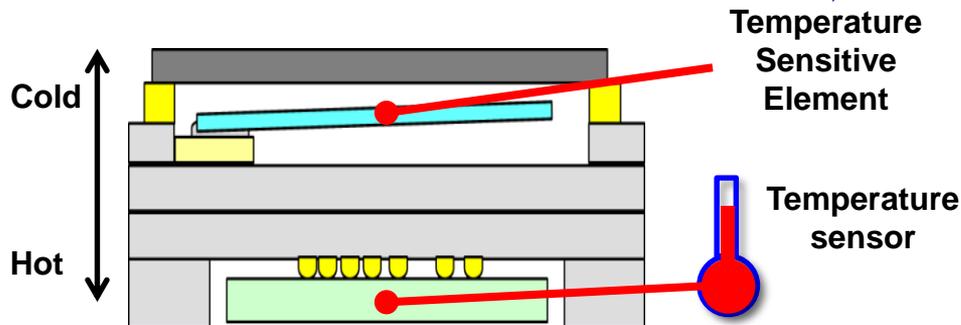


Epson QMEMS (photolithographic)

Differences in crystal chip shape



Why TCXOs are Sensitive to Airflow



PCB

Fundamental Mechanism

- Temperature-sensitive element (crystal) and temperature sensor (IC) are not in the same place

- Airflow causes Temperature gradient

- How sensitive is Quartz?

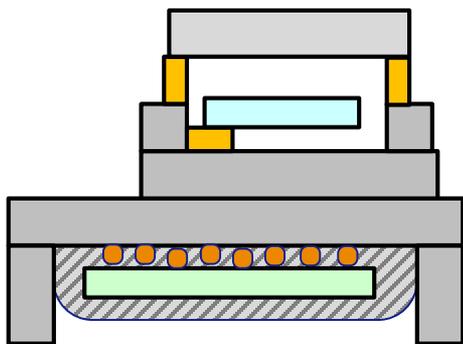
$$\frac{df}{dT} = \frac{20 \text{ ppm}}{60 \text{ }^\circ\text{C}} = 0.3 \text{ ppm}/^\circ\text{C}$$

vs. 30 ppm/°C for Silicon

- How much temperature gradient can we tolerate?

$$1 \text{ ppb} \div 0.3 \text{ ppm}/^\circ\text{C} = 0.003 \text{ }^\circ\text{C}$$

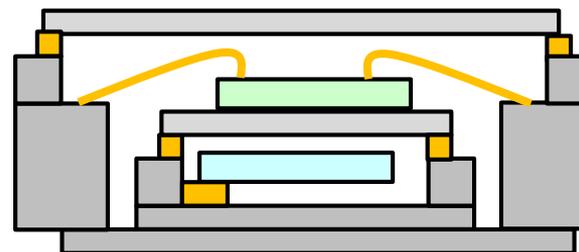
Construction – Double-Decker vs. DoubleSeal™



Double-Decker

Phase transients due to to airflow

- Crystal and IC not thermally coupled



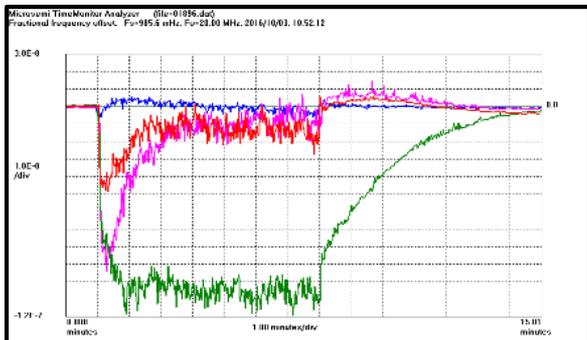
DoubleSeal™

Better Thermal Design

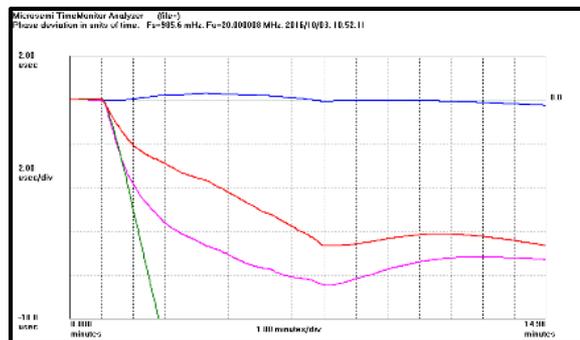
- Protected from airflow and board turbulence
- More stable for small T changes

US & Japanese patents

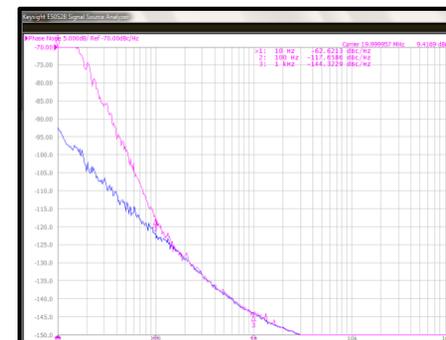
Performance under Airflow



Better Frequency Stability
3-25x



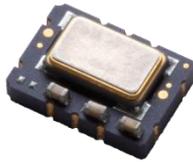
Better Phase Stability
1-250x



Better Phase Noise
30 dB @ 10 Hz

Dependable Synchronization

Comparison of Specs



**Conventional
TCXOs**

**DoubleSeal™
TCXO**

**Future
TCXO**

**Current
OCXOs**

Aging	±3 ppm	±3 ppm	<< 1 ppm	±1 ppm
Initial	±1 ppm	±1 ppm	±1 ppm	±500 ppb
vs. T	±0.1-0.28 ppm	±0.1-0.28 ppm →	±10 ppb	±10 ppb
vs. V	±0.1 ppm	±0.1 ppm →	±10 ppb ✓	±10 ppb
vs. C _L	±0.1 ppm	±0.1 ppm →	±10 ppb ✓	±10 ppb
TOTAL	< ±4.6 ppm	< ±4.6 ppm	< ±4.6 ppm	< ±4.6 ppm
24-hour drift	±40 ppb	±5 ppb →	±1 ppb	< ±1 ppb
ADEV (1s)	1E-9	2E-10 →	1E-10	0.5-1E-10

So how close are we? Next Steps?

Where are we now?

- TCXOs easily meet S3, but not S3E
- Many PTP systems need OCXOs
- TCXOs getting a **lot** better

Solved problems

- Greatly improved wander due to improved crystal design
- Airflow issues solved with thermal design techniques
- 24-hour drift getting a **lot** better, approaching OCXOs

What's next?

- Improve f vs. T through calibration techniques – ± 100 ppb \rightarrow ± 10 ppb
- Further improvement of wander and 24-hour drift

How soon can this be done?

THANK YOU

Allan Armstrong
Chris McCormick
Abbas Hage
Yuichi Toriumi
Yasuo Maruyama

Tomonori Oya
Takuya Owaki
Naohisa Obata
Katsuhito Nakajima
Hideo Haneda
Yasuhiro Sudo

Masayuki Ishikawa
Atsushi Kiyohara
Mihiro Nonoyama
Satoru Kodaira
Takashi Kumagai

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